

CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)Applicant(s): **Aderl**

Docket No.

1549.001

Serial No.

09/786,809

Filing Date

7/3/01

Examiner

Zarneke

Group Art Unit

2827

Invention:

METHOD FOR PRODUCING A HYBRID FRAME OR HOUSING...

I hereby certify that this Amendment, transmittal, IDS, etc.
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on July 24, 2003

(Date)

Wanda Ruggiera

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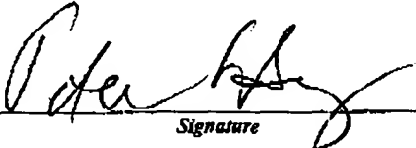
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AMENDMENT TRANSMITTAL LETTER (Large Entity)			Docket No. 1549.001		
Applicant(s): Anderl					
Serial No. 09/786,809	Filing Date July 3, 2001	Examiner Zarneke	Group Art Unit 2827		
Invention: METHOD FOR PRODUCING A HYBRID FRAME OR HOUSING...					
<u>TO THE COMMISSIONER FOR PATENTS:</u>					
Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below.					
CLAIMS AS AMENDED					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	6 -	20 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	1 -	3 =	0 x	\$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00
<div style="display: flex; justify-content: space-between;"><div><input checked="" type="checkbox"/> No additional fee is required for amendment. <input type="checkbox"/> Please charge Deposit Account No. _____ in the amount of _____ <input type="checkbox"/> A check in the amount of _____ to cover the filing fee is enclosed. <input checked="" type="checkbox"/> The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 02-2105 <input checked="" type="checkbox"/> Any additional filing fees required under 37 C.F.R. 1.16. <input checked="" type="checkbox"/> Any patent application processing fees under 37 CFR 1.17.</div><div style="text-align: right;">02-2105 02-2105 02-2105</div></div>					
 Signature			Dated: July 24, 2003		
<div style="display: flex; justify-content: space-between;"><div>Peter L. Berger, Esq. (Reg. No. 24,570) LEVISOHN, LERNER, BERGER & LANGSAM, LLP 757 Third Avenue, Suite 2500 New York, NY 10017 Phone: (212) 486-7272 Fax: (212) 486-0323</div><div style="border: 1px solid black; padding: 5px; width: 30%; text-align: center;"><small>I certify that this document and fee is being deposited on 7/24/03 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.</small> <small>Signature of Person Mailing Correspondence</small> Wanda Ruggiera <small>Typed or Printed Name of Person Mailing Correspondence</small></div></div>					
CC:					

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Application of: Anderl
Serial No.: 09/786,809
Art Unit: 2827
Examiner: Zameke
Filing Date: July 3, 2001

July 24, 2003

For: Method for producing a hybrid frame or
housing.....
Attorney Docket No.: 1549.001

VIA FAX (703) 872-9318

Hon. Commissioner for Patents
Washington, D.C. 20231

AMENDMENT

Sir:

In response to the Official Action of June 25, 2003, please amend this
application as follows:

In the Claims:

1. A method for producing a hybrid frame or hybrid housing in which a
leadframe having electrical connecting surfaces ~~with soldering and/or bonding tags~~ after
being placed in an injection moulding die is moulded with plastic to form a housing part
of the hybrid frame or the hybrid housing, characterized in that the ~~soldering and/or~~
~~bonding tags~~ electrical connection surfaces of the leadframe are held down in the
injection moulding die for the compensation of surface defects at least during a part of
the injection moulding process by means of a stamp.

3. The method according to claim 2, characterized in that the electrical
connecting surfaces ~~soldering and/or bonding tags~~ are form-stamped during the
moulding process.

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